



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Charles W.C. Lin

Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA

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Examiner: Graybill, D. Group Art Unit: 2827

Atty. Docket No.: P002-2

COMMISSIONER FOR PATENTS

P.O. Box 1450

Alexandria, VA 22313-1450

RESPONSE

In response to the Office Action dated September 23, 2004, please amend the application as follows.

The Claim Amendments begin at page 2.

The Remarks begin at page 17.